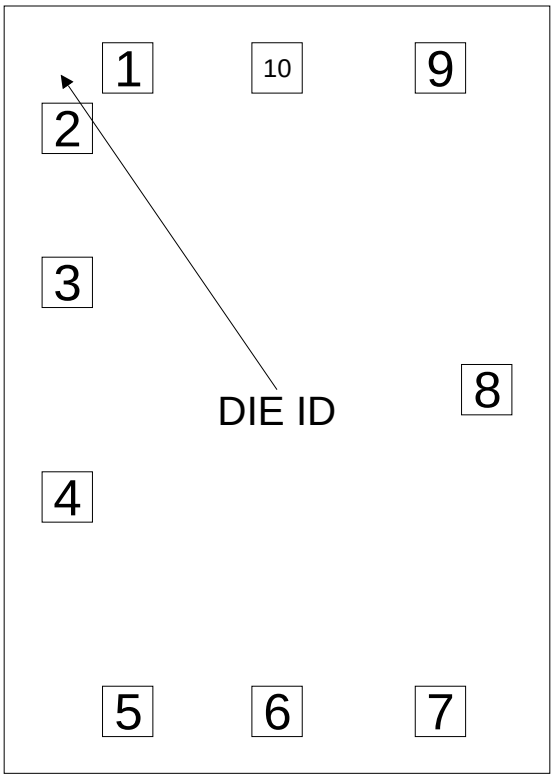
LMP7716Q MDA MWA
DUAL PRECISION, 17 MHZ, LOW NOISE, CMOS INPUT AMPLIFIER

MAY 07, 2008

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LMP7716A	Bond Pad Opening Size (min)	75.00µm x 75.00µm
Die Step	A	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	150mm	Back Side Metal	BAREBACK
Die Size (Drawn)	812.80µm x 1143.00µm 32.0mils x 45.0mils	Back Side Connection	Floating
Thickness	254µm Nominal		
Min Pitch	223µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(A-Step)
(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X		Y
IN A +	1	-222	479	75	x	75
V -	2	-312	389	75	x	75
NC	3	-312	159	75	x	75
NC	4	-312	-159	75	x	75
IN B +	5	-222	-479	75	x	75
IN B -	6	0	-479	75	x	75
OUT B	7	243	-479	75	x	75
V +	8	312	0	75	x	75
OUT A	9	243	479	75	x	75
IN A -	10	0	479	75	x	75

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Notes

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